



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



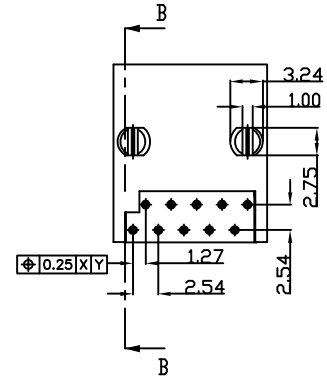
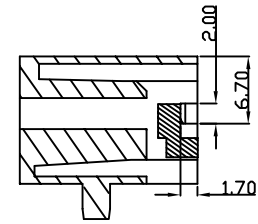
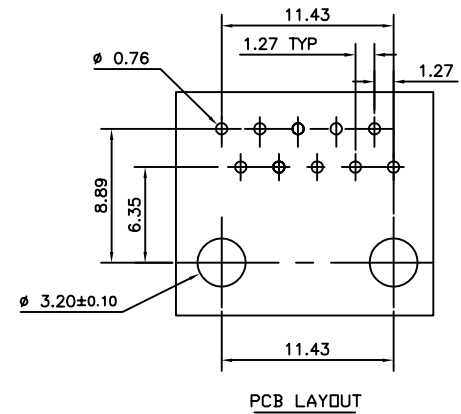
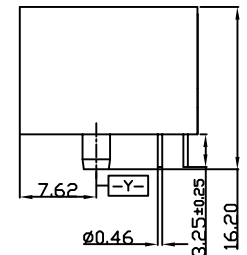
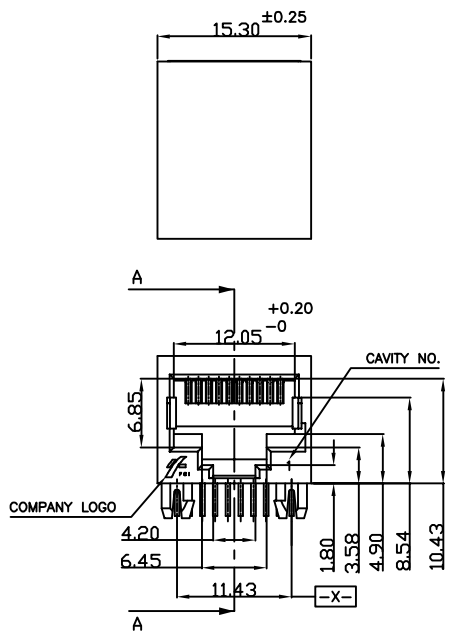
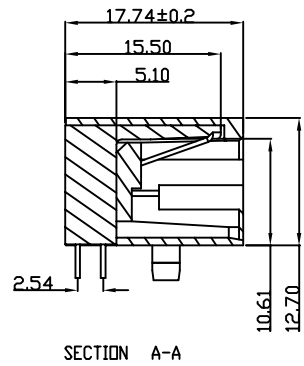


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1.LF Products meet European Union Directives and other country Regulations as described in GS-22-008.

2.The Housing will withstand exposure to 260° peak temperature for 3.5 sec in a wave solder application with a 1.6mm Min thick circuit board. Slight deformation of snap pegs may occur at 260-265°c which will not affect the function of the product.

3.Lead Free or ROHS Directive labelling to be provided as per GS-14-920 for Lead Free version.



TECHNICAL SPECIFICATION

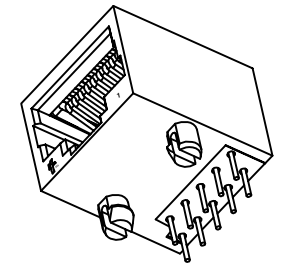
- Insulation Resistance - 500 M Ohms min.
- Dielectric Strength - 1000 V rms , 60 Hz.
- Contact Resistance - 20 milli,Ohms. max.
- Current Rating - 1.5 amp DC
- Maximum Total Mating Force - 35 N
- Retention Force Between Plug & Jack - 22.5 N min.
- Durability - 500 mating cycles
- Temperature Range -25 / + 90 Deg C.

Material:
Housing : PBT 30% Glass Filled UL 94 V-0 Black

The housing will withstand exposure to 260-265°C for 3.5 seconds in a wavesoldering application. Use protective adhesive tape (Kapton or Teflon) or protective metallic devices on the areas which are directly exposed to wave soldering as it is used in classical leaded wave soldering.

Contact : Ø0.46mm Phosphor Bronze
Plating :
Active zone : Gold over nickel on contact area
Termination zone : SnPb over Nickel (Leaded vesion)
: Matte Tin over nickel (Lead Free version)

PART NO. 54602-X10 LF
LEAD FREE
6-0.76 µ Au.Sel.
7-Au Flash.Sel.
8-1.27 µ Au.Sel.
9-0.38 µ Au.Sel.



NOTES:

- 1. ALL WIRES MUST BE STRAIGHT TO THE SHELF

mat'l. code		surface		tolerance		projection		product family	
-		ISO 1302		ISO 406 ISO 1101		MM		MODJACK	
ltr		ecn no		dr		date		title	
D		106-0123		HVN		2006-07-21		10 POL SHALLOW LATCH CONNECTOR	
E		107-0039		HVN		2007-03-16		(PCB.MODJACK)	
F		107-0122		HVN		2007-09-19		scale	
angles		linear		±1°		MM		dwg no	
dr		MINI K VANDANATH		2003-04-04		FCI		sheet 1 of 1	
enrg		HIRAN.V.N		2003-04-04		A3		size	
chr		HIRAN.V.N		2007-09-19		C-BMJ-0101		type	
appd		HIRAN.V.N		2007-09-19		Product Customer Drawing		Drawing	
sheet index		revision sheet		F		1		5	